

DNU
1-2 september 2011

**Civa as
Cieva AB
Vika Technology**

Civa as

Location: Eidsvåg i Romsdal, Norway

Per Sverre Røed, Manager

Siri K. Kvernberg, Logistic/Accounting

Cieva AB

Location: Stockholm, Sweden

Claes Williander, Marketing Manager

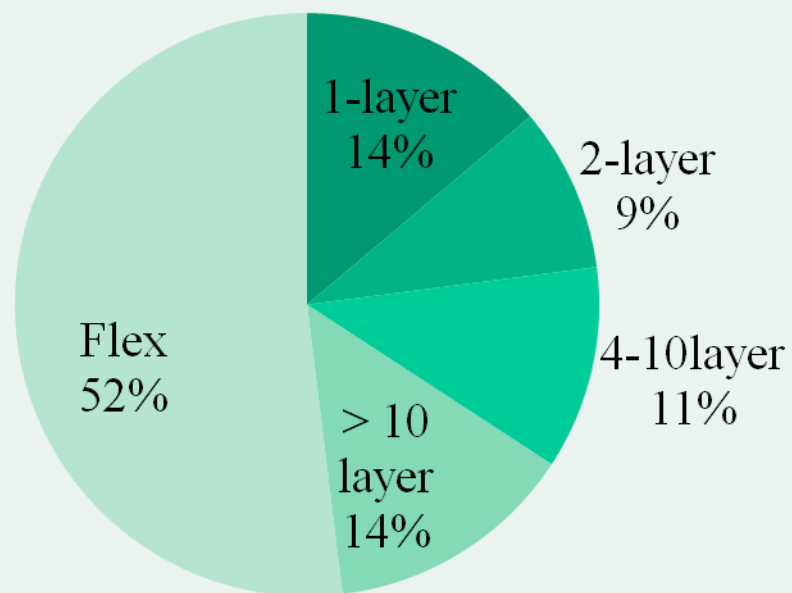
Vika Technology Ltd.
Location: Shenzhen, China

Titan Wang, Site Manager
Henry Tong, CAM Specialist
Coco Deng, Logistic

Turnover all companies

1000 kr	2009	2010
Turnover	15.430	20.365
EBIT	48	419

Sales 2011



Civa as is **AT&S** sales representative
in Scandinavia.

Many exiting technologies

2.5D[®] Technology Platform

2.5DC Cavity

Local Thickness
Reduction

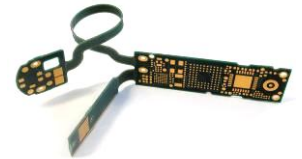


2.5DP Pipe

2.5DR Rigid-Flexible (Flex to install)

Outermost Layers
(FR4 and /or PI)

Centre Layers
(FR4 and /or PI)

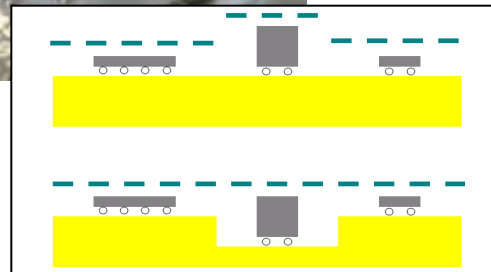
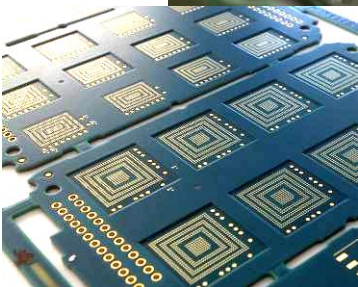
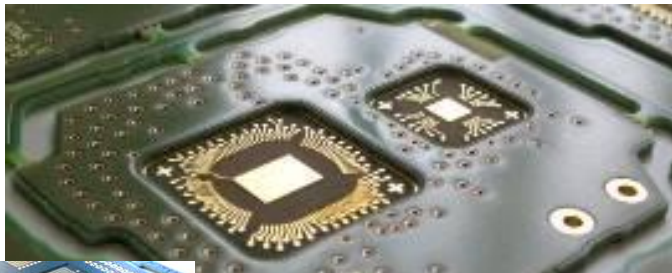
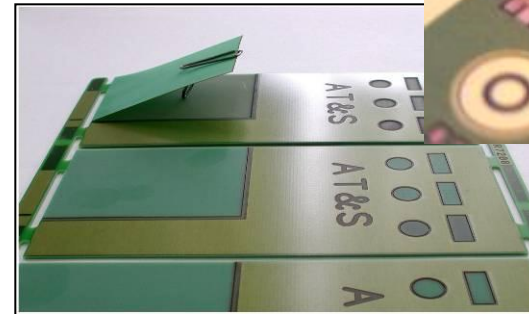
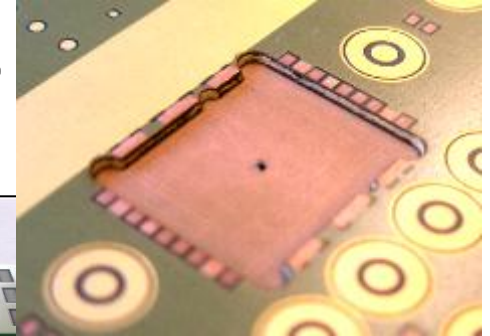


what you can use it for..

1) Cavities

A) Local thickness reduction

- Usage of standard FR4 materials & HDI designrules
- No additional cutting required (routing, punching,...)
- No limitations in cavity shape
- Various depths can be combined on one PCB
- Standard production process



B) Component placement in cavity

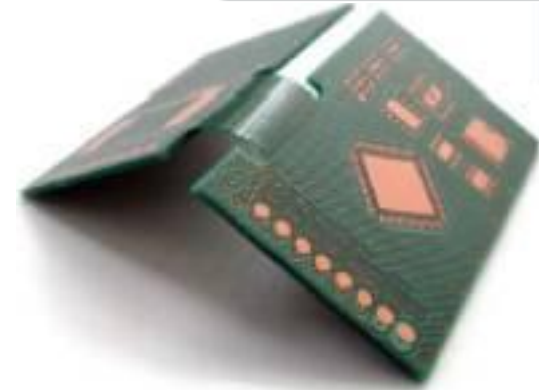
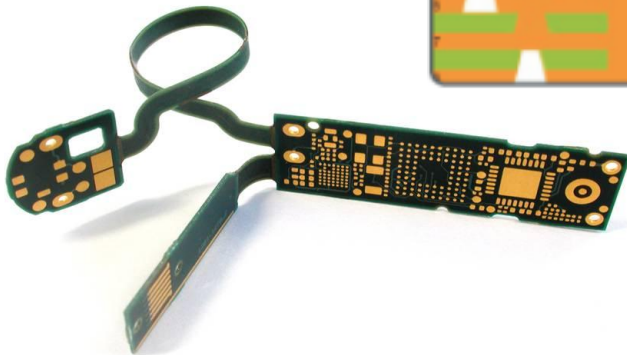
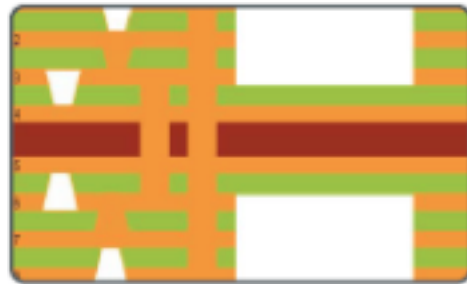
- Same advantages as Option A
- Assembly in cavity
- With or without soldermask possible
- Fan-out happens on assembly layer

what you can use it for..

2) “Semiflex” (flex-to-install) & RigidFlex technology

A) HDI “Semiflex”

- Usage of standard FR4 materials & HDI designrules
- Well known reliability (bending cycles can be pre-evaluated)
- Symmetrical build-up
- Very cost competitive for “flex-to-install” OR non-dynamic applications



B) Advanced RigidFlex

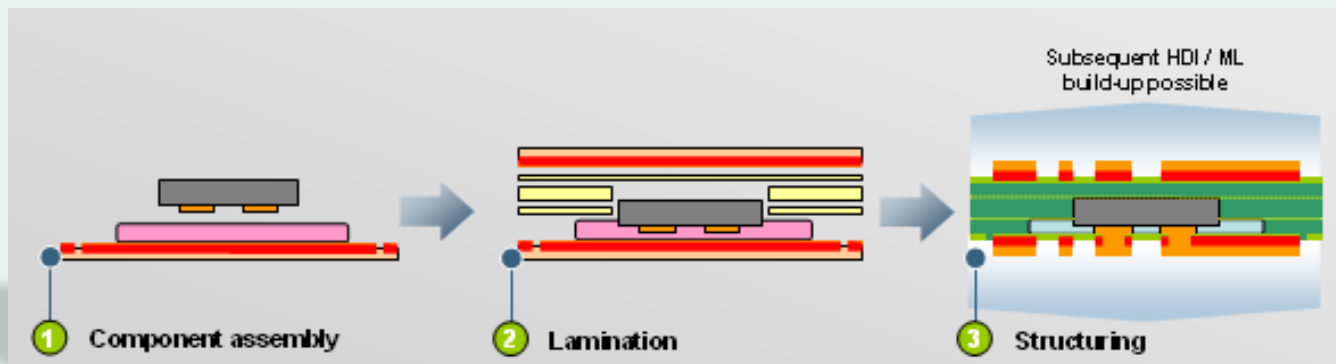
- Combination Polyimide & FR4 materials
- No additional cutting required (routing, punching,...)
- Standard production process
- Suitable for dynamic applications

AT&S Main event 2011
Embedded Component Packaging
ECP®

AT&S has started volume production of embedded under the brand ECP® A new factory has been build in Loeben, Austria

ECP® is the commercially available result of more than 10 years R&D, in partnership with Industry leaders (most recently under the HERMES EU funded project)

ECP® is the leading chip embedding technology



ECP® for

- * increased reliability**
- * improved signal integrity**
- * further miniaturization**
- * higher security**

Find out more:
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